



P.C.B LAYOUT MOUNTING PATTERN

NOTES:

1.MATERIAL:

- 1.1 HOUSING: LCP
- 1.2 CONTACT: BRASS
- 1.3 SHELL: SUS

2.Finish:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: TIN UNDER PLATED SURFACE LAYER

3.SPECIFICATION:

- 3.1 CURRENT RATING: 2.0 A MAX
- 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 V(ac) FOR 1min
- 3.3 CONTACT RESISTANCE: 50 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.
- 3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.
- 3.7 TEMPERATURE RANGE: -30°C ~ +80°C



TOLERANCE UNLESS OTHERWISE STATED:
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3°

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	08/28/17			
CHECKED BY:	DATE	FINISH	MODLE	MICRO USB 5B/F 180度 SMT
Jacky Chen	08/28/17			
APPROVED BY:	DATE	SCALE	DWG NO.	MRUSB-5B-VS4-S316
Tony Kao	08/28/17	1 : 1	PART NO.	MRUSB-5B-VS4-S316
		SHEET NO.	1 of 1	
				SIZE A4
				VER R2